

Material Data Sheet

MKD AC Film Capacitor

Product Class		FilterCap MKD AC: B32377 type B							
Date		November 1 st , 2019							
IMDS ID if available									
Version		01		B32377 type B					
Product Part (IMDS: semi component)		Material Class (IMDS: Material)			Substance		CAS if applicable	Typical mass of material [wt-%]	Traces see 1)
Active Part		Polymer	2A	Polypropylene		100	9003-07-0	36.5	
		Heavy Metal	1C	Zn	Zn		7440-66-6	9.4	
		•		others*):		2			
Encapsulation	n	Polymer	2A	DMC		100	23165-19-7	7	
Encapsulation		Polymer	2A	PBT		100	26062-94-2	2.1	
		,	,				9004-34-6		
	_	Paper,Cardboard	6D	Cellulose		100		0.8	
		Polymer	2C	Polyurethar	ne resin	100	9003-29-6	26.7	
		Light Metal	1B	AI		100	7429-90-5	11.2	
		Polymer	2A	PE		100	24937-78-8	0.45	
		Polymer	2A	PA66		100	24936-68-3	1.8	
		Elastomer	2B	Silicon		100	7440-21-3	0.3	
Termination		Metal	1A	Steel		100	7439-89-6	1.6	
		Metal	1C	Brass		100	7440-31-5	0.3	
		Metal	1C	Sn		100	7440-31-5	0.93	
		Metal	1C	Copper		100	7440-50-8		
			-					0.9	
		Metal	1C	Ni		100	7440-02-0	0.02	
							Sum in total:	100	
Sizes DxH[mm] 96x169~136x356		Weight range [kg] 1.3~5.5					Part numbers: B32377X		
Not Part of a	Product	Class							
Contact	Dennis	Huang			Important rema	rks:			
Division	TDK (Z	DK (Zhuhai FTZ) Co., Ltd 1) The declaration limit is 0.1% as defined by IEC 62474 (IEC PAS 61906). Traces a							
Address	No.4 Lia CHINA	anfeng Road, Xiang	zhou District, 519030 Zh	nuhai City PR	hai City PR 2) product parts, substances etc. that are below a percentage of 0.1 % by weigh otherwise regulated. This Material Data Sheet contains typical values of the respective products s				
Tel: +8		756 886 3112 r	nailto: dennis.huang@tdk-electr	ronics.tdk.com	ics.tdk.com herein. We expressly point out that all values and statements contained herein a				
*) others: .(not declarable or prohibited substances acc. GADSL)					based on our best present knowledge and cannot be regarded as binding statements or binding product specifications, unless otherwise explicitly agreed in writing. TDK				
**) typical mas	s percen	tage of substance			ELECTRONICS AG AND ITS AFFILIATES HEREBY EXPRESSLY DISCLAIM ANY REPRESENTATION OR WARRANTY, WHETHER EXPRESS, IMPLIED OR STATUTORY, WITH REGARD TO THE STATEMENTS AND VALUES CONTAINED HEREIN, INCLUDING BUT NOT LIMITED TO ANY REPRESENTATION OR WARRANTY OF MERCHANTABILITY OR SUITABILITY FOR ANY PURPOSE.				
								ording to Art. 4 (substance re	
			and of the Council of June s / Product according				aruous sudstances	in electrical and electronic e	quipment.
 ☑ no exemptions □ Exemption 6 (a) 	s;		·						
 Exemption 6 (a): Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0,35 % lead by weight; Exemption 6 (b): Lead as an alloying element in aluminum containing up to 0,4 % lead by weight; 									
Exemption 6 (c): Copper alloy containing up to 4 % lead by weight;									
Exemption 7 (a): Lead in high melting temperature type solder (i.e. lead-based alloys containing 85 % by weight or more lead);									
Exemption 7 (c)-I: Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound;									
Exemption 7 (c)-II: Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher;									
			itors for a rated voltage of less t			rated circuit Elia (hin nackacos:		
C Exemption 15: Other Exemption		solders to complete a viable	e electrical connection between		anu carrier within integ	rateu circuit FIIP (omp packages;		